

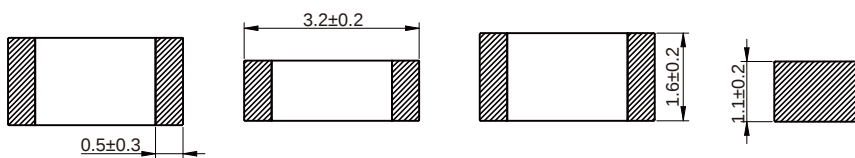
Chip Ferrite Bead SMD Type Size 1206



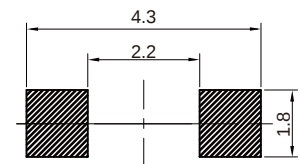
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▪ Quan ty: 3000pcs

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Dimensions: [mm]



Land Pattern: [mm]

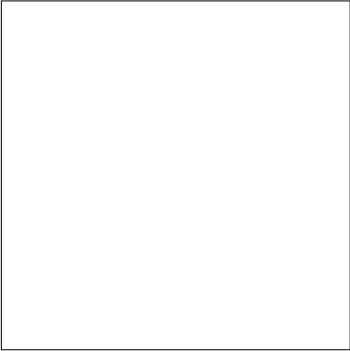
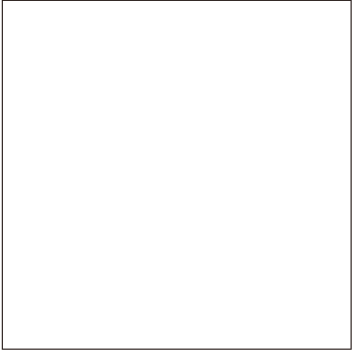
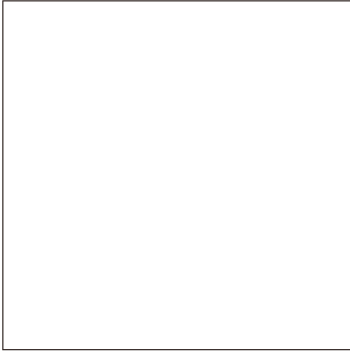
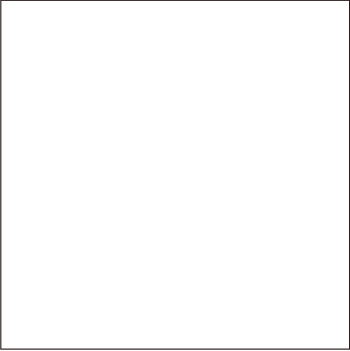
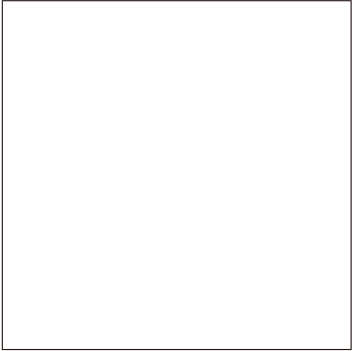
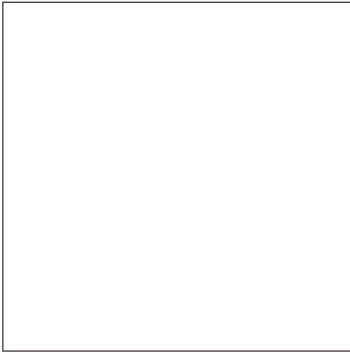
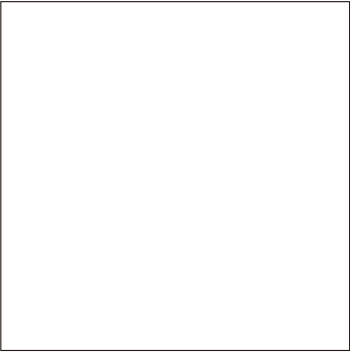
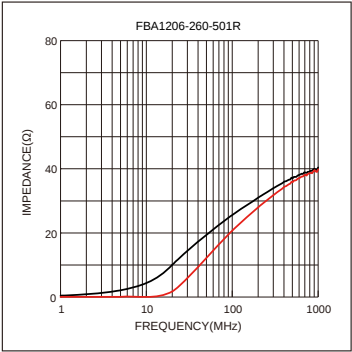


Electrical Properties:

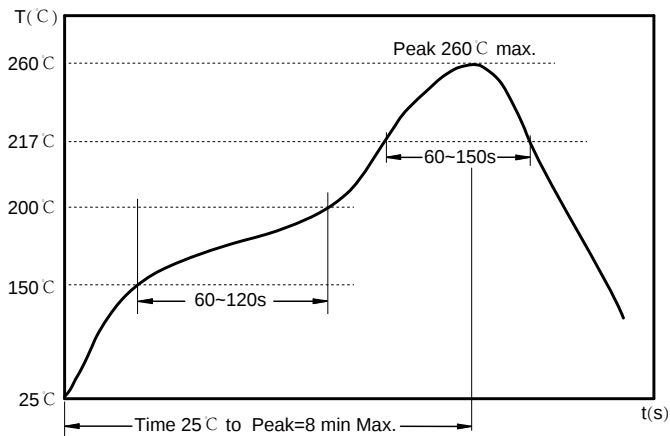
Part No	Z @ 100 MHz (Ω)	Tolerance	R _{DC} (Ω)	I _R (mA)
FBA1206-260-501R		±25%	0.20	500
FBA1206-310-501R		±25%	0.20	500
FBA1206-420-501R		±25%	0.20	500
FBA1206-500-501R		±25%	0.20	500
FBA1206-700-501R		±25%	0.20	500
FBA1206-900-501R		±25%	0.20	500
FBA1206-121-901R		±25%	0.15	900
FBA1206-151-901R		±25%	0.15	900
FBA1206-221-701R		±25%	0.35	700
FBA1206-301-701R		±25%	0.35	700
FBA1206-471		±25%	0.35	400

I_R referring to 20K self-heating above ambient temperature

Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

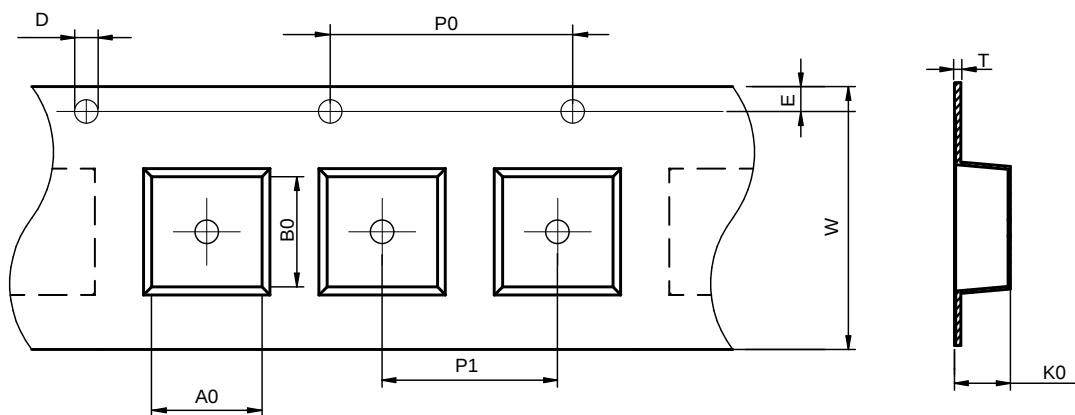
Allowed time above 217 °C : 60~150 sec.

Max temperature: 260 °C.

Allowed Reflow time: 3x max.

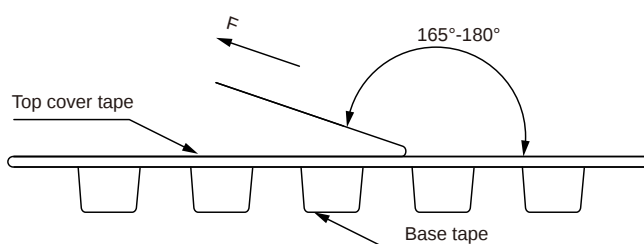
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
FBA1206	1.75±0.10	3.35±0.10	1.5±0.10	4.0±0.10	4.0±0.10	8.0±0.10	1.25±0.10	1.75±0.10	0.23±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.58 N

Reel Dimension: [mm]

